2016 Joint Applied Optics and Chinese Optics Letters
Feature Introduction: Digital Holography and 3D Imaging

This feature issue is the second Joint Applied Optics (AO) and Chinese Optics Letters (COL) Feature Issue on digital holography and three-dimensional (3D) imaging. The first installment of such a joint feature issue was in 2011. In the present feature issue, there are a total of 24 papers in AO and 9 papers in COL.

This feature issue contains a representative selection of topics that were presented at the OSA Topical Meeting on Digital Holography and 3D Imaging (DH), held in Shanghai, China, May 2015. The DH Topical Meeting is the world’s premier forum for science, technology, and applications of the digital holograph and three-dimensional imaging and display methods. The topic areas include interferometry, phase microscopy, novel holographic processes, 3D and novel displays, integral imaging, computer-generated holograms, compressive holography, full-field tomography, and holography with various light sources, including coherent to incoherent and x-ray to terahertz waves. This is a highly interdisciplinary forum with applications in biomedicine, biophotonics, nanomaterials, nanophotonics, and scientific and industrial metrologies.

All submitted papers, including invited papers, have undergone peer review. We hope these articles will present state-of-the-art technological developments that are currently under way and stimulate further novel applications of digital holography and 3D imaging.

The next DH meeting is scheduled to be held on July 25–28, 2016, at Heidelberg, Germany. DH 2017 will take place in Korea.

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